

OPAx180-Q1 0.1 μ V/ $^{\circ}$ C 漂移、低噪声、轨至轨输出、36V 零漂移 运算放大器

1 特性

- 符合汽车类应用的要求
- 具有符合 AEC-Q100 标准的下列特性：
 - OPA180-Q1 器件温度等级 1: -40°C 至 $+125^{\circ}\text{C}$ 环境运行温度范围
 - OPA2180-Q1 器件温度等级 2: -40°C 至 $+105^{\circ}\text{C}$ 环境运行温度范围
 - 器件 HBM ESD 分类等级 1C
 - 器件 CDM ESD 分类等级 C5
 - 宽电源电压: $\pm 2\text{V}$ 至 $\pm 18\text{V}$
 - 低失调电压: $75\mu\text{V}$ (最大值)
 - 零漂移: $0.1\mu\text{V}/^{\circ}\text{C}$
 - 低噪声: $10\text{ nV}/\sqrt{\text{Hz}}$
 - 极低 $1/f$ 噪声
 - 出色的直流精度:
 - 电源抑制比 (PSRR): 126dB
 - 共模抑制比 (CMRR): 114dB
 - 开环路增益 (A_{OL}): 120dB
 - 静态电流: $525\mu\text{A}$ (最大值)
 - 轨至轨输出: 输入包括负电源轨
 - 低偏置电流: 250pA (典型值)
 - 已过滤射频干扰 (RFI) 的输入
 - MicroSIZE 封装

2 应用范围

- 汽车高精度电流测量
- 车载充电器 (OBC)
- 电池管理系统 (BMS)
- 电机控制
- 牵引逆变器

3 说明

OPA180-Q1 和 OPA2180-Q1 运算放大器采用 TI 的专有零漂移技术，可同时提供低失调电压 ($75\mu\text{V}$)，并随时间推移和温度变化实现接近零漂移的性能。这些高精度、低静态电流微型运算放大器提供高输入阻抗和摆幅在电源轨 18mV 之内的轨至轨输出。输入共模范围包括负电源轨。电压范围为 4V 至 36V ($\pm 2\text{V}$ 至 $\pm 18\text{V}$) 的单电源或双电源均可使用。

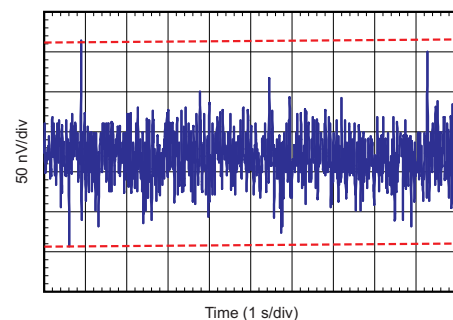
单通道和双通道版本均采用 VSSOP-8 封装。单封装产品 (OPA180-Q1) 的额定温度范围为 -40°C 至 $+125^{\circ}\text{C}$ ，双封装 (OPA2180-Q1) 的额定温度范围为 -40°C 至 $+105^{\circ}\text{C}$ 。

器件信息⁽¹⁾

器件名称	封装	封装尺寸 (标称值)
OPA180-Q1	VSSOP (8)	$3.00\text{mm} \times 3.00\text{mm}$
OPA2180-Q1	VSSOP (8)	$3.00\text{mm} \times 3.00\text{mm}$

(1) 如需了解所有可用封装，请参阅产品说明书末尾的可订购产品附录。

低噪声
(峰值到峰值噪声 = 250nV)



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4 修订历史记录

Changes from Original (June 2017) to Revision A	Page
• 已添加 在特性 列表中添加了 OPA180-Q1 和 OPA4180-Q1 器件温度等级	1
• 已更改 在特性 列表中将 OPA2180-Q1 器件温度等级从等级 1 更改为等级 2	1
• 已更改 在特性 列表中将 OPA2180-Q1 环境运行温度范围从“−40°C 至 +105°C”更改为“−40°C 至 +125°C”	1
• 已更改 在说明 部分中将 OPA180-Q1 和 OPA4180-Q1 运行温度从“−40°C 至 +105°C”更改为“−40°C 至 +125°C”	1
• Changed input offset voltage drift temperature range from $T_A = -40^\circ\text{C}$ to 105°C to $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ in <i>Electrical Characteristics</i> table	8
• Changed power supply rejection ratio temperature range from $T_A = -40^\circ\text{C}$ to 105°C to $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ in <i>Electrical Characteristics</i> table	8
• Changed OPA180-Q1 input bias current temperature range from $T_A = -40^\circ\text{C}$ to 105°C to $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ in <i>Electrical Characteristics</i> table	8
• Changed OPA180-Q1 input offset current temperature range from $T_A = -40^\circ\text{C}$ to 105°C to $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ in <i>Electrical Characteristics</i> table	8
• Changed common-mode rejection ratio temperature range from $T_A = -40^\circ\text{C}$ to 105°C to $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ in <i>Electrical Characteristics</i> table	8
• Changed open-loop voltage gain temperature range from $T_A = -40^\circ\text{C}$ to 105°C to $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ in <i>Electrical Characteristics</i> table	8
• Changed voltage output swing from rail temperature range from $T_A = -40^\circ\text{C}$ to 105°C to $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ in <i>Electrical Characteristics</i> table	9
• Changed quiescent current temperature range from $T_A = -40^\circ\text{C}$ to 105°C to $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ in <i>Electrical Characteristics</i> table	9
• 已更改 operating temperature from “−40°C to +105°C” to “−40°C to +125°C” in <i>Feature Description</i> section	16
• Updated 图 34	22

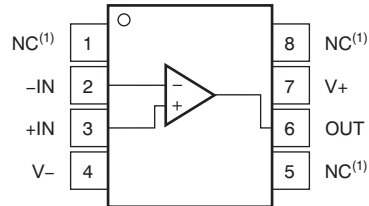
5 Device Comparison Table

Table 1. Zero-Drift Amplifier Portfolio

VERSION	PRODUCT	OFFSET VOLTAGE (μV)	OFFSET VOLTAGE DRIFT ($\mu\text{V}/^\circ\text{C}$)	BANDWIDTH (MHz)
Single	OPA188-Q1 (4 V to 36 V)	25	0.085	2
	OPA180-Q1 (4 V to 36 V)	75	0.35	2
	OPA333 (5 V)	10	0.05	0.35
	OPA378 (5 V)	50	0.25	0.9
	OPA735 (12 V)	5	0.05	1.6
Dual	OPA2188-Q1 (4 V to 36 V)	25	0.085	2
	OPA2180-Q1 (4 V to 36 V)	75	0.35	2
	OPA2333 (5 V)	10	0.05	0.35
	OPA2378 (5 V)	50	0.25	0.9
	OPA2735 (12 V)	5	0.05	1.6
Quad	OPA4188 (4 V to 36 V)	25	0.085	2
	OPA4180 (4 V to 36 V)	75	0.35	2
	OPA4330 (5 V)	50	0.25	0.35

6 Pin Configuration and Functions

**OPA180-Q1 DGK Package
8-Pin VSSOP
Top View**

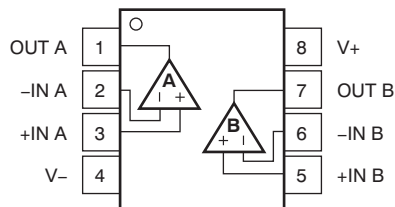


(1) NC- no internal connection

Pin Functions: OPA180-Q1

PIN		DESCRIPTION
NAME	NO.	
-IN	2	Inverting input
+IN	3	Noninverting input
NC	1, 5, 8	No connection
OUT	6	Output
V-	4	Negative power supply
V+	7	Positive power supply

**OPA2180-Q1 DGK Package
8-Pin VSSOP
Top View**



Pin Functions: OPA2180-Q1

PIN		DESCRIPTION
NAME	NO.	
-IN A	2	Inverting input, channel A
+IN A	3	Noninverting input, channel A
-IN B	6	Inverting input, channel B
+IN B	5	Noninverting input, channel B
OUT A	1	Output, channel A
OUT B	7	Output, channel B
V-	4	Negative power supply
V+	8	Positive power supply

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
	Supply voltage		±20, ±40 (single-supply)	V
	Signal input terminals	Voltage	(V ₋) – 0.5 (V ₊) + 0.5	V
		Current	±10	mA
	Output short-circuit ⁽²⁾	Continuous		
	Operating temperature	–55	125	°C
T _J	Junction temperature		150	°C
T _{stg}	Storage temperature	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Short-circuit to ground, one amplifier per package.

7.2 ESD Ratings

		VALUE	UNIT
V _(ESD) Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	±1500	V
	Charged-device model (CDM), per AEC Q100-011	±750	

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted), R_L = 10 kΩ connected to V_S / 2, and V_{COM} = V_{OUT} = V_S / 2, (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage [(V ₊) – (V ₋)]	Single-supply	4.5		36	V
	Bipolar-supply	±2.25		±18	V
Operating temperature		–40		125	°C

7.4 Thermal Information: OPA180-Q1

THERMAL METRIC ⁽¹⁾		OPA180-Q1	UNIT
		DGK (VSSOP)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	180.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case(top) thermal resistance	67.9	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	102.1	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	10.4	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	100.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case(bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Thermal Information: OPA2180-Q1

THERMAL METRIC ⁽¹⁾		OPA2180-Q1	UNIT
		DGK (VSSOP)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	159.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	37.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	48.5	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	1.2	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	77.1	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

OPA180-Q1, OPA2180-Q1

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7.6 Electrical Characteristics: $V_S = \pm 2\text{ V}$ to $\pm 18\text{ V}$ ($V_S = 4\text{ V}$ to 36 V)

 at $T_A = 25^\circ\text{C}$, $R_L = 10\text{ k}\Omega$ connected to $V_S / 2$, and $V_{\text{COM}} = V_{\text{OUT}} = V_S / 2$, (unless otherwise noted)

PARAMETER			CONDITIONS		MIN	TYP	MAX	UNIT
OFFSET VOLTAGE								
V _{IO}	Input offset voltage					15	75	μV
dV _{IO} /dT	Input offset voltage drift		T _A = −40°C to +125°C			0.1	0.35	μV/°C
PSRR	Power-supply rejection ratio		V _S = 4 V to 36 V V _{CM} = V _S / 2			0.1	0.5	μV/V
			T _A = −40°C to +125°C, V _S = 4 V to 36 V V _{CM} = V _S / 2				0.5	μV/V
	Long-term stability					4 ⁽¹⁾		μV
	Channel separation, DC					1		μV/V
INPUT BIAS CURRENT								
I _{IB}	Input bias current		OPA2180-Q1			±0.25	±1	nA
			OPA2180-Q1: T _A = −40°C to +105°C		18		±5	nA
			OPA180-Q1			±0.25	±1.7	nA
			OPA180-Q1: T _A = −40°C to +125°C		18		±6	nA
I _{IO}	Input offset current		OPA2180-Q1			±0.5	±2	nA
			OPA2180-Q1: T _A = −40°C to +105°C		6		±2.5	nA
			OPA180-Q1				±3.4	nA
			OPA180-Q1: T _A = −40°C to +125°C		6		±3	nA
NOISE								
	Input voltage noise		f = 0.1 Hz to 10 Hz			0.25		μV _{PP}
e _n	Input voltage noise density		f = 1 kHz			10		nV/√Hz
i _n	Input current noise density		f = 1 kHz			10		fA/√Hz
INPUT VOLTAGE RANGE								
V _{CM}	Common-mode voltage range				V−		(V+) − 1.5	V
CMRR	Common-mode rejection ratio		(V−) < V _{CM} < (V+) − 1.5 V		104	114		dB
			T _A = −40°C to +125°C (V−) + 0.5 V < V _{CM} < (V+) − 1.5 V		100	104		dB
INPUT IMPEDANCE								
Z _{id}	Differential					100 6		MΩ pF
Z _{ic}	Common-mode					6 9.5		10 ¹² Ω pF
OPEN-LOOP GAIN								
A _{OL}	Open-loop voltage gain		(V−) + 500 mV < V _O < (V+) − 500 mV R _L = 10 kΩ		110	120		dB
			T _A = −40°C to +125°C (V−) + 500 mV < V _O < (V+) − 500 mV R _L = 10 kΩ		104	114		dB
FREQUENCY RESPONSE								
GBW	Gain bandwidth product					2		MHz
SR	Slew rate		G = 1			0.8		V/μs
t _s	Settling time	0.1%	V _S = ±18 V, G = 1, 10-V step			22		μs
		0.01%	V _S = ±18 V, G = 1, 10-V step			30		μs
t _{or}	Overload recovery time		V _{IN} × G = V _S			1		μs
THD+N	Total harmonic distortion + noise		f = 1 kHz, G = 1, V _{OUT} = 1 V _{RMS}			0.0001%		

 (1) 1000-hour life test at 125°C demonstrated randomly distributed variation in the range of measurement limits, or approximately $4\text{ }\mu\text{V}$.

Electrical Characteristics: $V_S = \pm 2\text{ V}$ to $\pm 18\text{ V}$ ($V_S = 4\text{ V}$ to 36 V) (continued)

at $T_A = 25^\circ\text{C}$, $R_L = 10\text{ k}\Omega$ connected to $V_S / 2$, and $V_{\text{COM}} = V_{\text{OUT}} = V_S / 2$, (unless otherwise noted)

PARAMETER		CONDITIONS	MIN	TYP	MAX	UNIT
OUTPUT						
Voltage output swing from rail		No load	8		18	mV
		$R_L = 10\text{ k}\Omega$	250		300	mV
		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ $R_L = 10\text{ k}\Omega$	325		360	mV
I_{OS}	Short-circuit current		± 18			mA
r_o	Output resistance (open loop)	$f = 2\text{ MHz}$, $I_O = 0\text{ mA}$	120			Ω
C_{LOAD}	Capacitive load drive		1			nF
POWER SUPPLY						
V_S	Operating voltage range		± 2 (or 4)	± 18 (or 36)		V
I_Q			450		525	μA
		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ $I_O = 0\text{ mA}$			600	μA
TEMPERATURE						
Specified range			-40		105	$^\circ\text{C}$
Operating range			-40		105	$^\circ\text{C}$

7.7 Typical Characteristics: Table of Graphs

表 2. Characteristic Performance Measurements

DESCRIPTION	FIGURE
I_B and I_{OS} vs Common-Mode Voltage	图 1
Input Bias Current vs Temperature	图 2
Output Voltage Swing vs Output Current (Maximum Supply)	图 3
CMRR vs Temperature	图 4
0.1-Hz to 10-Hz Noise	图 5
Input Voltage Noise Spectral Density vs Frequency	图 6
Open-Loop Gain and Phase vs Frequency	图 7
Open-Loop Gain vs Temperature	图 8
Open-Loop Output Impedance vs Frequency	图 9
Small-Signal Overshoot vs Capacitive Load (100-mV Output Step)	图 10, 图 11
No Phase Reversal	图 12
Positive Overload Recovery	图 13
Negative Overload Recovery	图 14
Small-Signal Step Response (100 mV)	图 15, 图 16
Large-Signal Step Response	图 17, 图 18
Large-Signal Settling Time (10-V Positive Step)	图 19
Large-Signal Settling Time (10-V Negative Step)	图 20
Short-Circuit Current vs Temperature	图 21
Maximum Output Voltage vs Frequency	图 22
Channel Separation vs Frequency	图 23
EMIRR IN+ vs Frequency	图 24

7.8 Typical Characteristics

$V_S = \pm 18\text{ V}$, $V_{CM} = V_S / 2$, $R_{LOAD} = 10\text{ k}\Omega$ connected to $V_S / 2$, and $C_L = 100\text{ pF}$, unless otherwise noted.

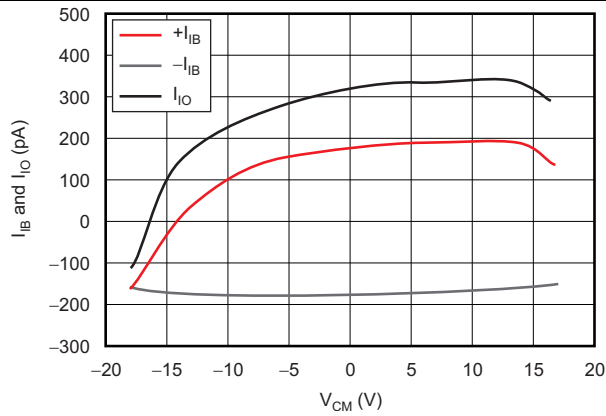


图 1. I_{IB} and I_{IO} vs Common-Mode Voltage

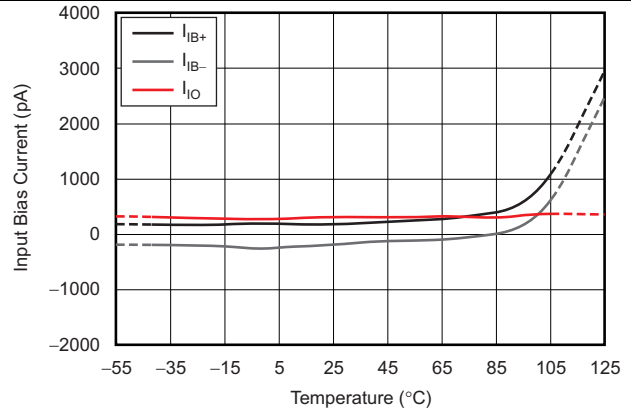


图 2. Input Bias Current vs Temperature

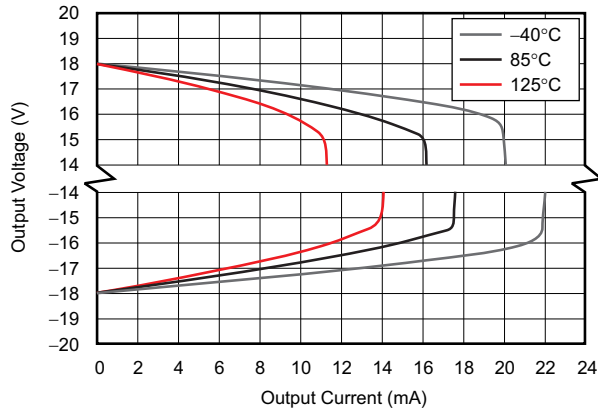
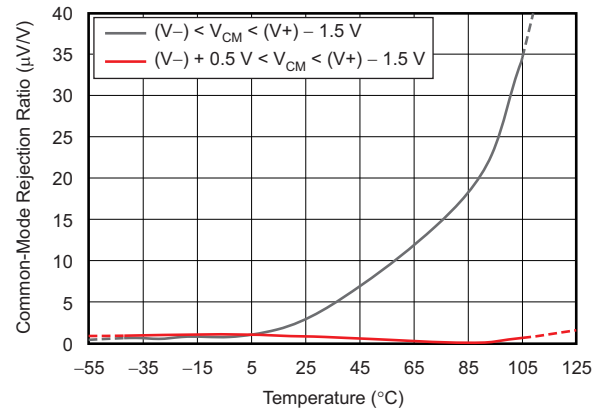


图 3. Output Voltage Swing vs Output Current (Maximum Supply)



$V_{SUPPLY} = \pm 2\text{ V}$

图 4. CMRR vs Temperature

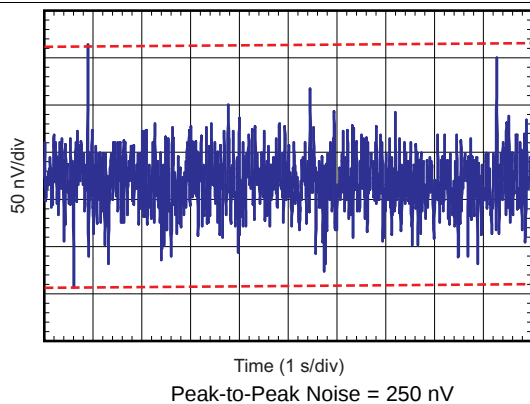


图 5. 0.1-Hz to 10-Hz Noise

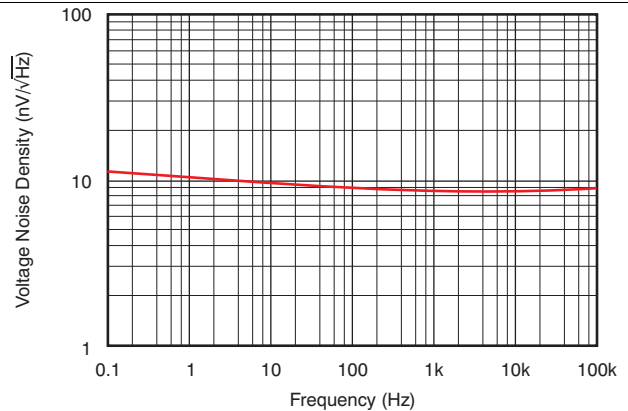


图 6. Input Voltage Noise Spectral Density vs Frequency

Typical Characteristics (接下页)

$V_S = \pm 18\text{ V}$, $V_{CM} = V_S / 2$, $R_{LOAD} = 10\text{ k}\Omega$ connected to $V_S / 2$, and $C_L = 100\text{ pF}$, unless otherwise noted.

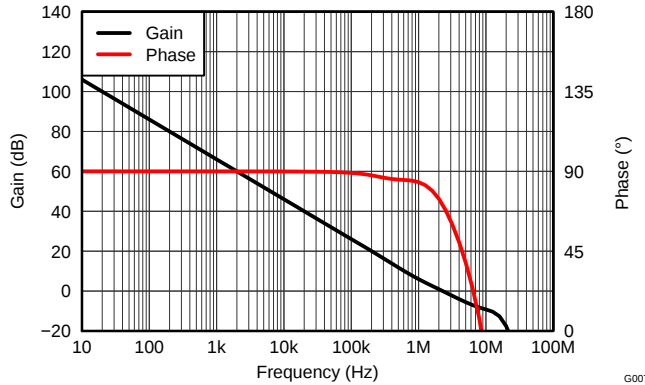


图 7. Open-Loop Gain and Phase vs Frequency

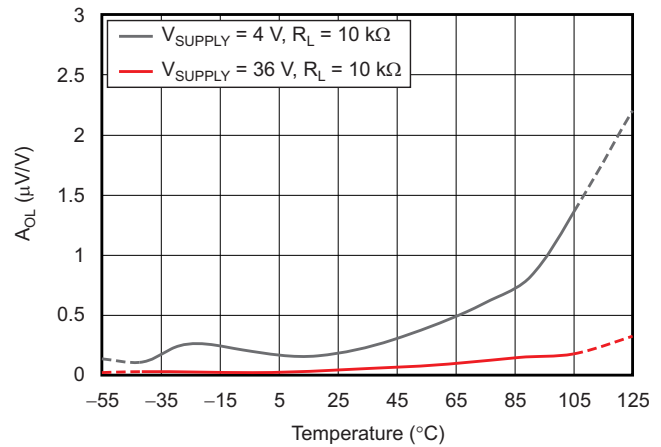


图 8. Open-Loop Gain vs Temperature

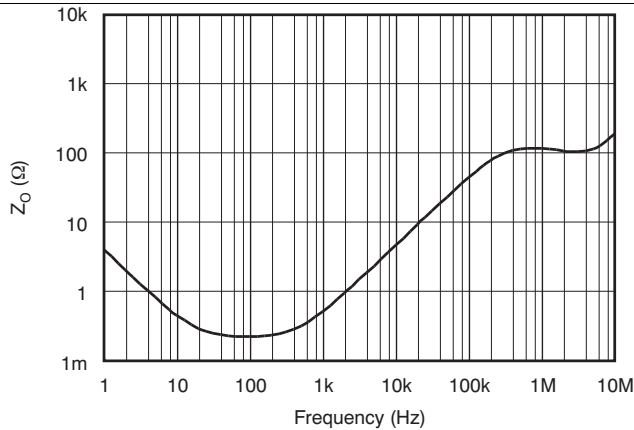


图 9. Open-Loop Output Impedance vs Frequency

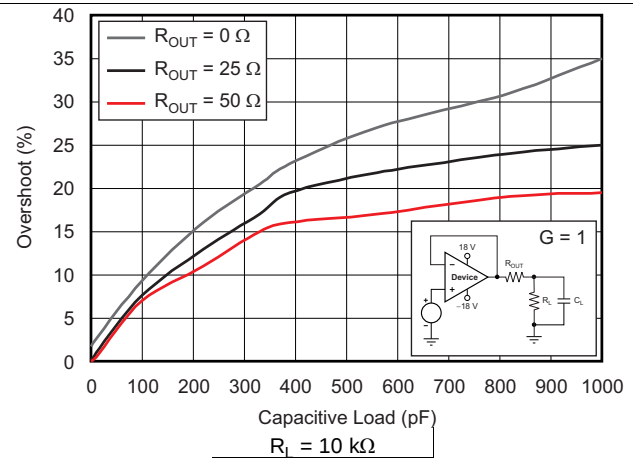
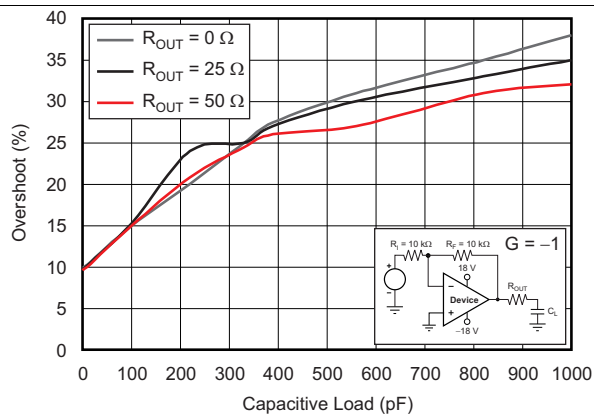


图 10. Small-Signal Overshoot vs Capacitive Load (100-mV Output Step)



$R_L = 10\text{ k}\Omega$

图 11. Small-Signal Overshoot vs Capacitive Load (100-mV Output Step)

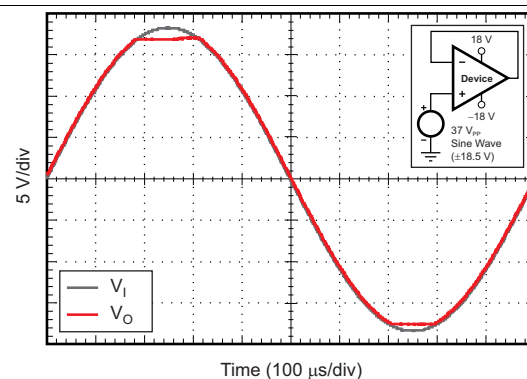


图 12. No Phase Reversal

Typical Characteristics (接下页)

$V_S = \pm 18\text{ V}$, $V_{CM} = V_S / 2$, $R_{LOAD} = 10\text{ k}\Omega$ connected to $V_S / 2$, and $C_L = 100\text{ pF}$, unless otherwise noted.

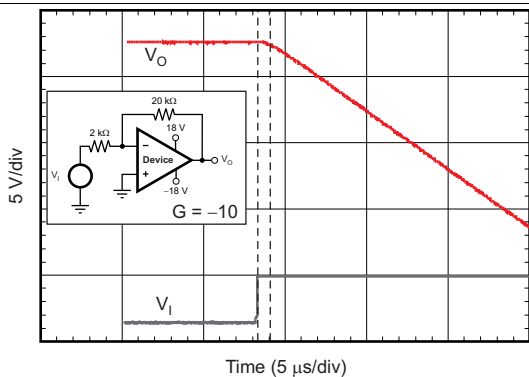


图 13. Positive Overload Recovery

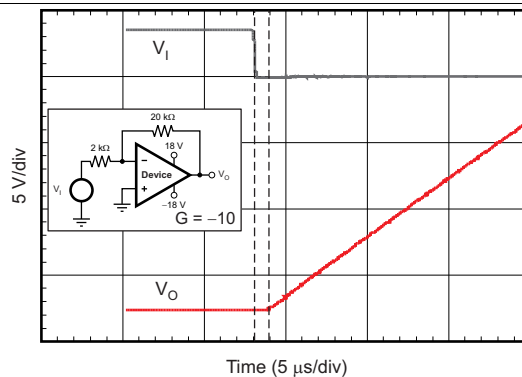


图 14. Negative Overload Recovery

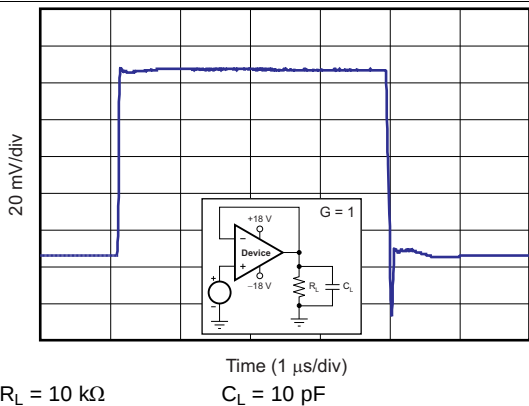


图 15. Small-Signal Step Response (100 mV)

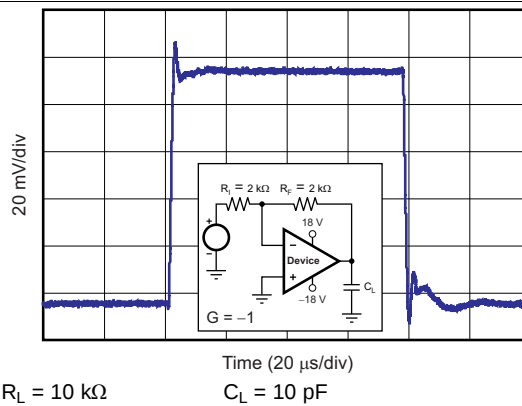


图 16. Small-Signal Step Response (100 mV)

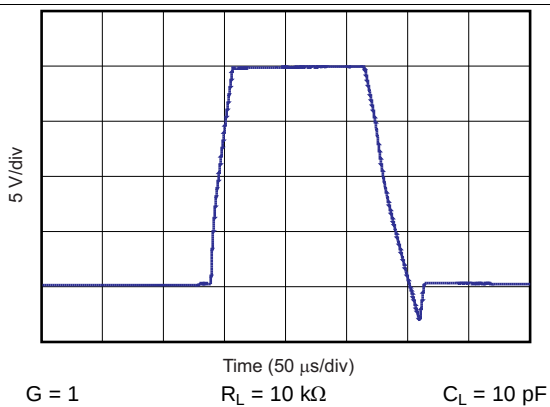


图 17. Large-Signal Step Response

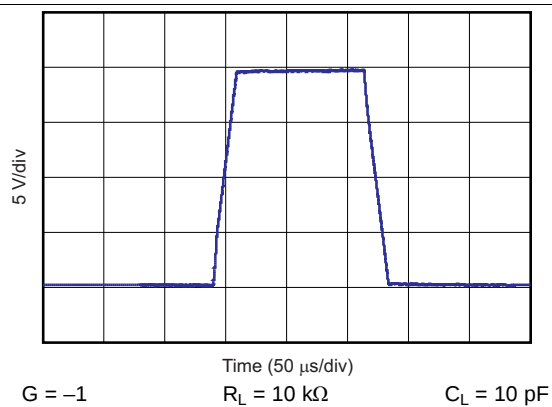
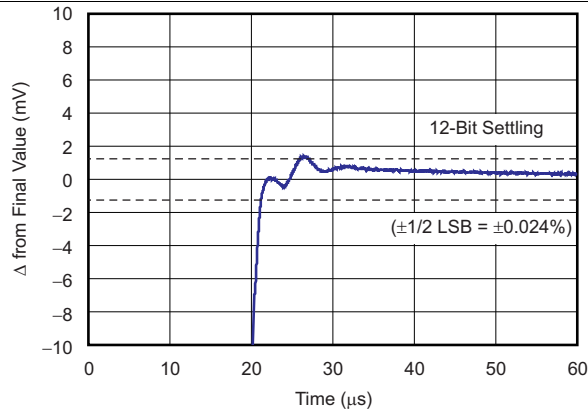


图 18. Large-Signal Step Response

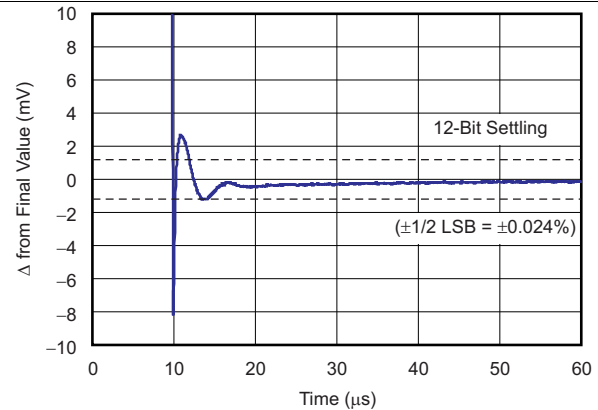
Typical Characteristics (接下页)

$V_S = \pm 18\text{ V}$, $V_{CM} = V_S / 2$, $R_{LOAD} = 10\text{ k}\Omega$ connected to $V_S / 2$, and $C_L = 100\text{ pF}$, unless otherwise noted.



$G = -1$

图 19. Large-Signal Settling Time (10-V Positive Step)



$G = -1$

图 20. Large-Signal Settling Time (10-V Negative Step)

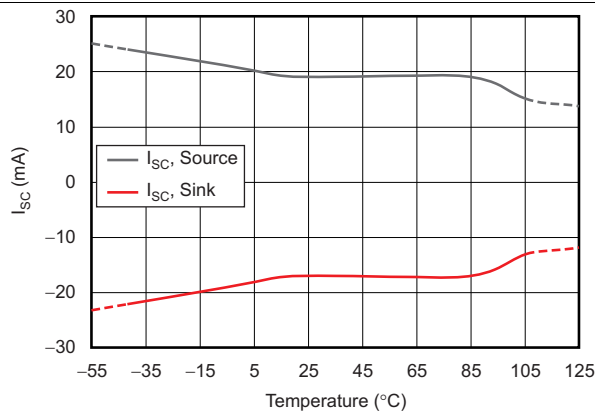


图 21. Short-Circuit Current vs Temperature

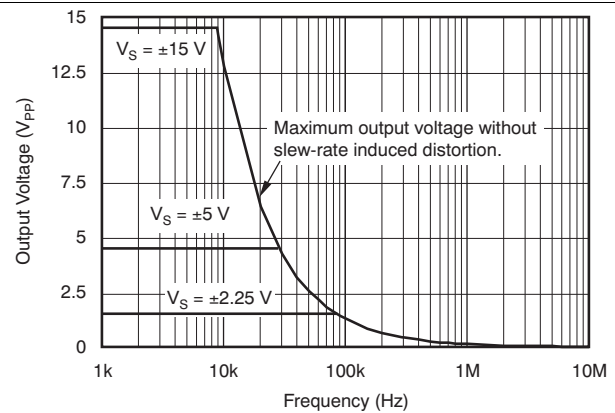


图 22. Maximum Output Voltage vs Frequency

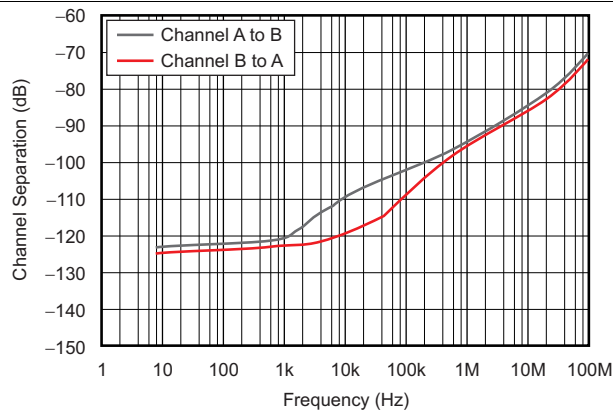


图 23. Channel Separation vs Frequency

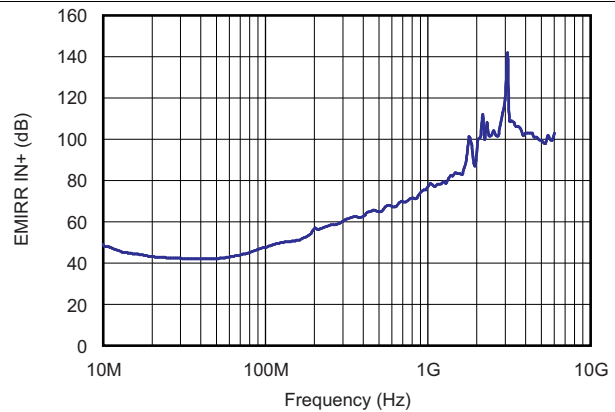


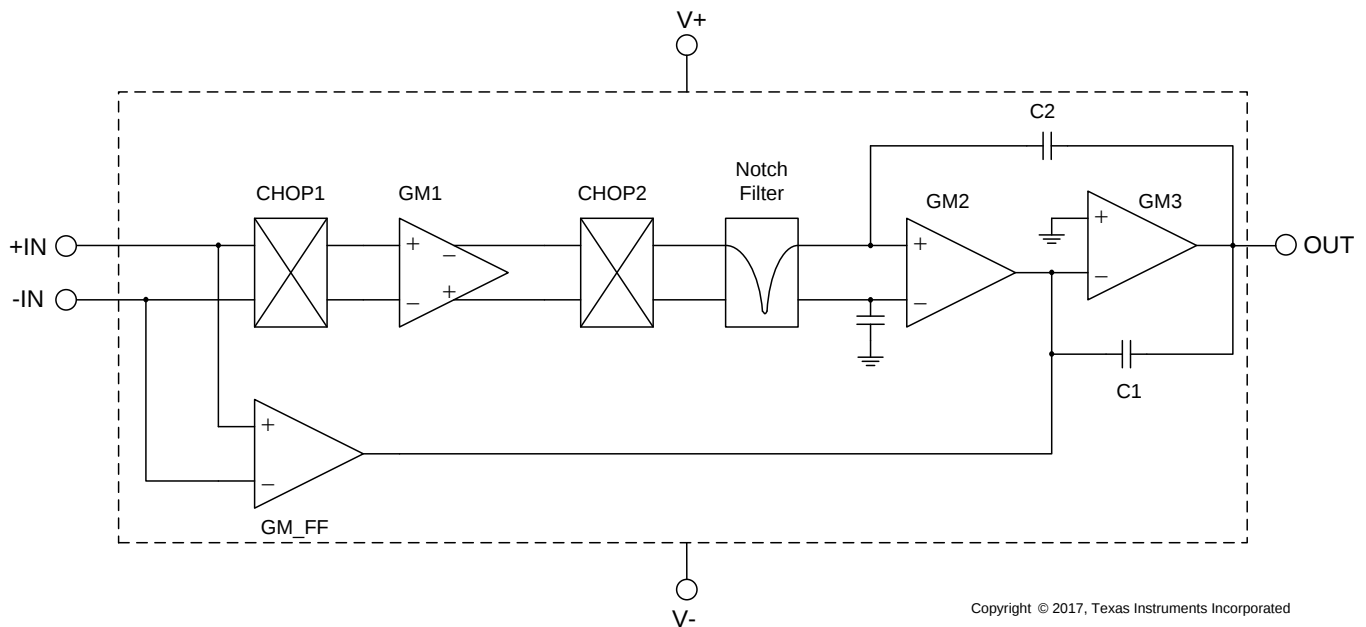
图 24. EMIRR IN+ vs Frequency

8 Detailed Description

8.1 Overview

The OPAX180-Q1 family of operational amplifiers combine precision offset and drift with excellent overall performance, making them designed for many precision applications. The precision offset drift of only $0.1 \mu\text{V}/^\circ\text{C}$ provides stability over the entire temperature range. In addition, the devices offer excellent overall performance with high CMRR, PSRR, and A_{OL} . As with all amplifiers, applications with noisy or high-impedance power supplies require decoupling capacitors close to the device pins. In most cases, $0.1\text{-}\mu\text{F}$ capacitors are adequate.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Operating Characteristics

The OPAx180-Q1 family of amplifiers is specified for operation from 4 V to 36 V (± 2 V to ± 18 V). Many of the specifications apply from -40°C to $+125^{\circ}\text{C}$. Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in the [Typical Characteristics](#).

8.3.2 EMI Rejection

The OPAx180-Q1 family uses integrated electromagnetic interference (EMI) filtering to reduce the effects of EMI interference from sources such as wireless communications and densely populated boards with a mix of analog signal chain and digital components. EMI immunity can improve with circuit design techniques; the OPAx180-Q1 family benefits from these design improvements. Texas Instruments has developed the ability to accurately measure and quantify the immunity of an operational amplifier over a broad frequency spectrum extending from 10 MHz to 6 GHz. 图 25 shows the results of this testing on the OPAx180-Q1 family. For more detailed information, see the [EMI Rejection Ratio of Operational Amplifiers](#) application report, available for download from www.ti.com.

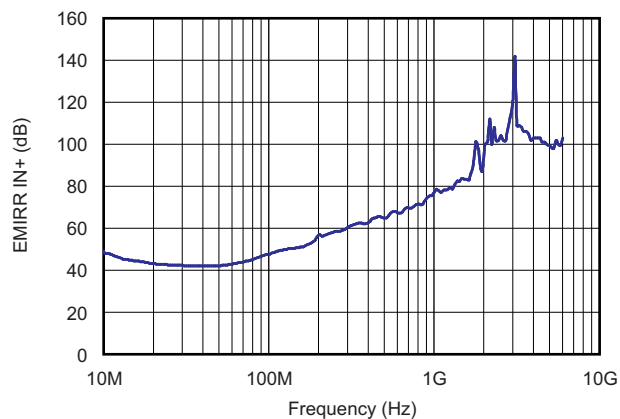


图 25. OPAx180-Q1 EMIRR Testing

8.3.3 Phase-Reversal Protection

The OPAx180-Q1 family has an internal phase-reversal protection. Many op amps exhibit a phase reversal when the input is driven beyond the linear common-mode range. This condition is most often encountered in noninverting circuits when the input is driven beyond the specified common-mode voltage range, causing the output to reverse into the opposite rail. The input of the OPAx180-Q1 prevents phase reversal with excessive common-mode voltage. Instead, the output limits into the appropriate rail. This performance is shown in 图 26.

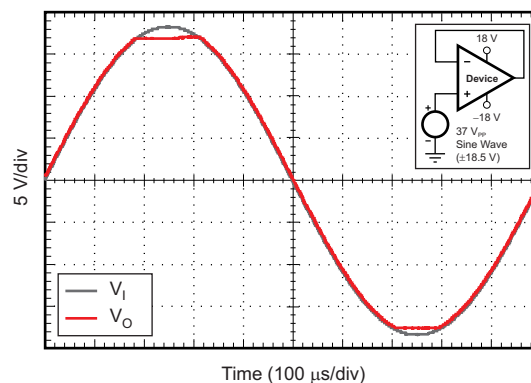
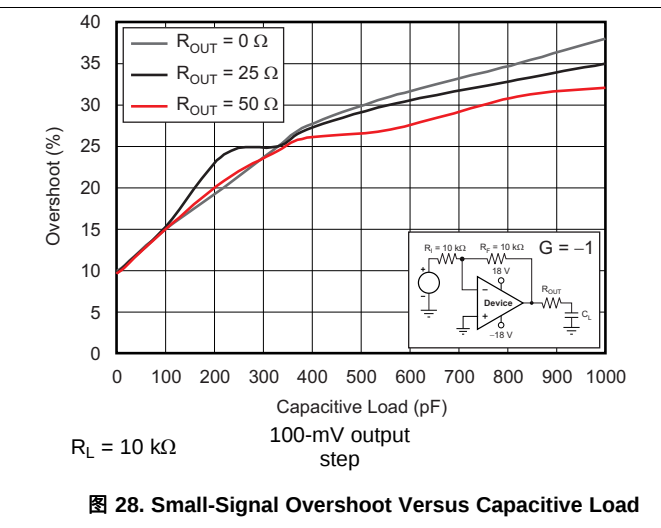
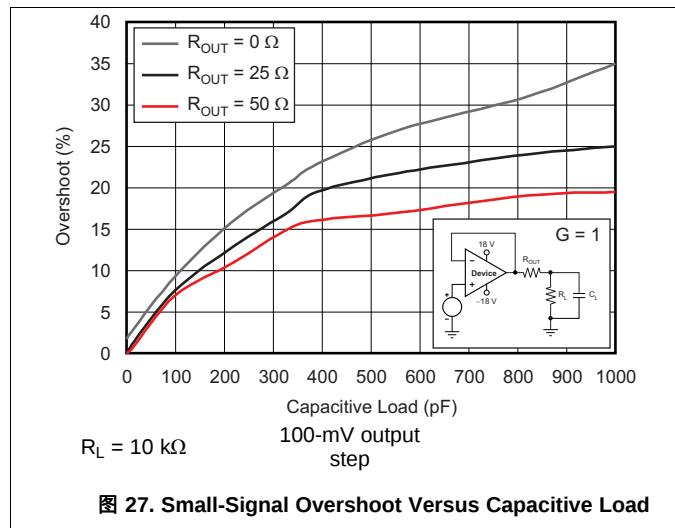


图 26. No Phase Reversal

Feature Description (接下页)

8.3.4 Capacitive Load and Stability

The dynamic characteristics of the OPAx180-Q1 are optimized for a range of common operating conditions. The combination of low closed-loop gain and high capacitive loads decreases the phase margin of the amplifier and can lead to gain peaking or oscillations. As a result, heavier capacitive loads must be isolated from the output. The simplest way to achieve this isolation is to add a small resistor (for example, R_{OUT} equal to 50 Ω) in series with the output. 图 27 和 图 28 illustrate graphs of small-signal overshoot versus capacitive load for several values of R_{OUT} . See the [Feedback Plots Define Op Amp AC Performance](#), application report, available for download from the TI website, for details of analysis techniques and application circuits.



8.3.5 Electrical Overstress

Designers often ask questions about the capability of an operational amplifier to withstand electrical overstress. These questions tend to focus on the device inputs, but may involve the supply voltage pins or even the output pin. Each of these different pin functions have electrical stress limits determined by the voltage breakdown characteristics of the particular semiconductor fabrication process and specific circuits connected to the pin. Additionally, internal electrostatic discharge (ESD) protection is built into these circuits to protect them from accidental ESD events both before and during product assembly.

These ESD protection diodes also provide in-circuit, input overdrive protection, as long as the current is limited to 10 mA as stated in the [Absolute Maximum Ratings](#) table. 图 29 shows how a series input resistor may be added to the driven input to limit the input current. The added resistor contributes thermal noise at the amplifier input and the value must be kept to a minimum in noise-sensitive applications.

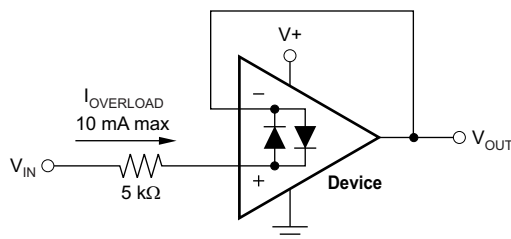


图 29. Input Current Protection

An ESD event produces a short duration, high-voltage pulse that is transformed into a short duration, high-current pulse as the pulse discharges through a semiconductor device. The ESD protection circuits are designed to provide a current path around the operational amplifier core to protect the core from damage. The energy absorbed by the protection circuitry is then dissipated as heat.

Feature Description (接下页)

When the operational amplifier connects into a circuit, the ESD protection components are intended to remain inactive and not become involved in the application circuit operation. However, circumstances may arise when an applied voltage exceeds the operating voltage range of a given pin. If this condition occurs, there is a risk that some of the internal ESD protection circuits may be biased on, and conduct current. Any such current flow occurs through ESD cells and rarely involves the absorption device.

If there is an uncertainty about the ability of the supply to absorb this current, external zener diodes may be added to the supply pins. The zener voltage must be selected so the diode does not turn on during normal operation.

However, the zener voltage must be low enough so that the zener diode conducts if the supply pin begins to rise above the safe operating supply voltage level.

8.4 Device Functional Modes

The OPAx180-Q1, and OPA2180-Q1 devices are powered on when the supply is connected. These devices can operate as a single-supply operational amplifier or dual-supply amplifier depending on the application. In single-supply operation with V_- at ground (0 V), V_+ can be any value between 4 V and 36 V. In dual-supply operation, the supply voltage difference between V_- and V_+ is from 4 V to 36 V. Typical examples of dual-supply configuration are ± 5 V, ± 10 V, ± 15 V, and ± 18 V. However, the supplies must not be symmetrical. Less common examples are V_- at -3 V and V_+ at 9 V, or V_- at -16 V and V_+ at 5 V. Any combination where the difference between V_- and V_+ is at least 4 V and no greater than 36 V is within the normal operating capabilities of these devices.

9 Application and Implementation

9.1 Application Information

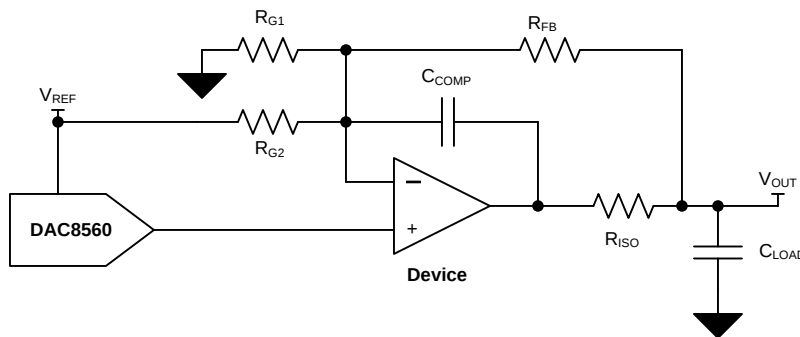
The OPAx180-Q1 family offers excellent DC precision and AC performance. These devices operate up to 36-V supply rails and offer rail-to-rail output, ultra-low offset voltage, offset voltage drift and 2-MHz bandwidth. These features make the OPAx180-Q1 a robust, high-performance amplifier for high-voltage industrial applications.

9.2 Typical Applications

These application examples highlight a few of the circuits where the OPAx180-Q1 family can be used.

9.2.1 Bipolar ± 10 -V Analog Output from a Unipolar Voltage Output DAC

This design is used for conditioning a unipolar digital-to-analog converter (DAC) into an accurate bipolar signal source using the OPAx180-Q1 family and three resistors. The circuit is designed with reactive load stability in mind, and is compensated to drive nearly any conventional capacitive load associated with long cable lengths.



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图 30. Circuit Schematic

9.2.1.1 Design Requirements

The design requirements are as follows:

- DAC Supply Voltage: 5-V DC
- Amplifier Supply Voltage: ± 15 -V DC
- Input: 3-Wire, 24-Bit SPI
- Output: ± 10 -V DC

Typical Applications (接下页)

9.2.1.2 Detailed Design Procedure

9.2.1.2.1 Component Selection

DAC: For convenience, devices with an external reference option or devices with accessible internal references are desirable in this application because the reference creates an offset. The DAC selection in this design must primarily be based on DC error contributions typically described by offset error, gain error, and integral nonlinearity error. Occasionally, additional specifications are provided that summarize end-point errors of the DAC typically called zero-code and full-scale errors. For AC applications, slew rate and settling time may require additional consideration.

Amplifier: Amplifier input offset voltage (V_{IO}) is a key consideration for this design. V_{IO} of an operational amplifier is a typical data sheet specification, but in-circuit performance is affected by drift over temperature, the common-mode rejection ratio (CMRR), and power-supply rejection ratio (PSRR). Consideration must be given to these parameters. For AC operation, additional considerations must be made for slew rate and settling time. Input bias current (I_{IB}) is also a factor, but typically the resistor network is implemented with sufficiently small resistor values that the effects of input bias current are negligible.

Passive: Resistor matching for the op-amp resistor network is critical for the success of this design; components with tight tolerances must be selected. For this design, 0.1% resistor values are implemented, but this constraint may be adjusted based on application-specific design goals. Resistor matching contributes to offset error and gain error in this design; see [Bipolar \$\pm 10V\$ Analog Output from a Unipolar Voltage Output DAC](#) for further details. The tolerance of the R_{ISO} and C_{COMP} stability components is not critical, and 1% components are acceptable.

9.2.1.3 Application Curves

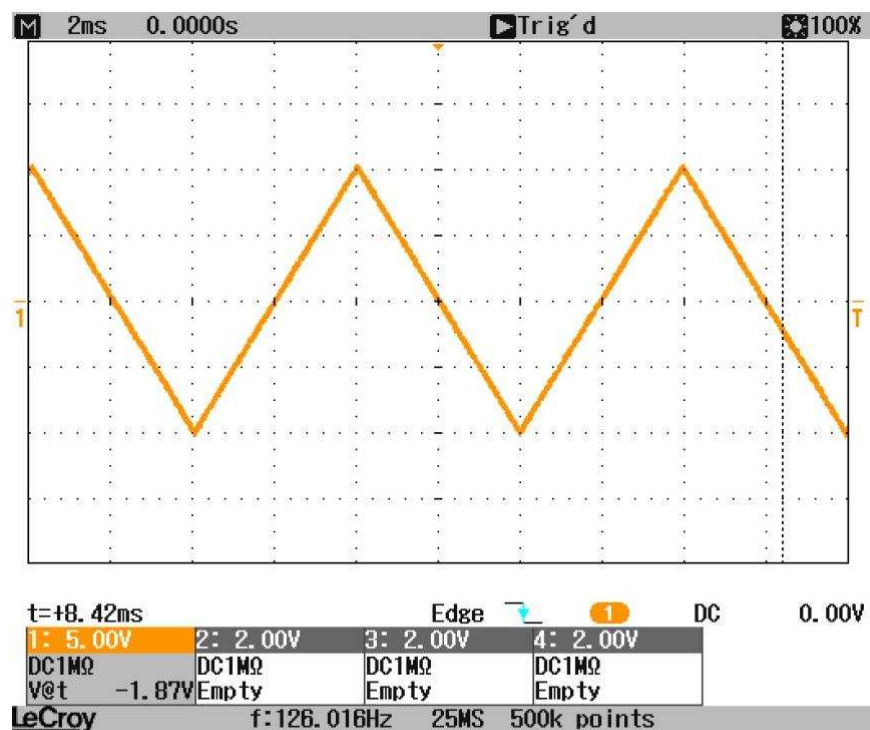


图 31. Full-Scale Output Waveform

Typical Applications (接下页)

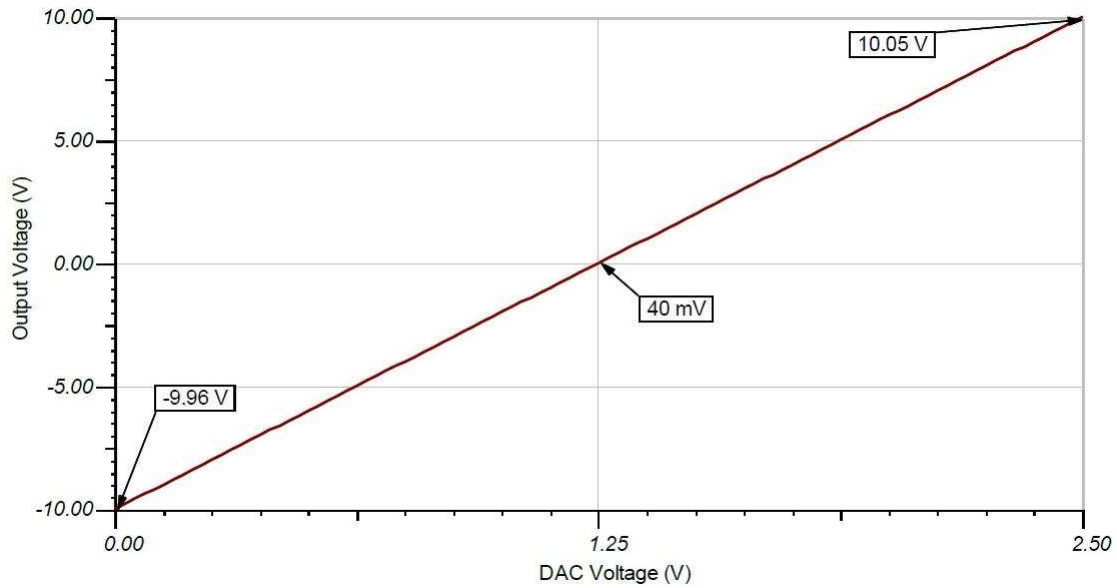


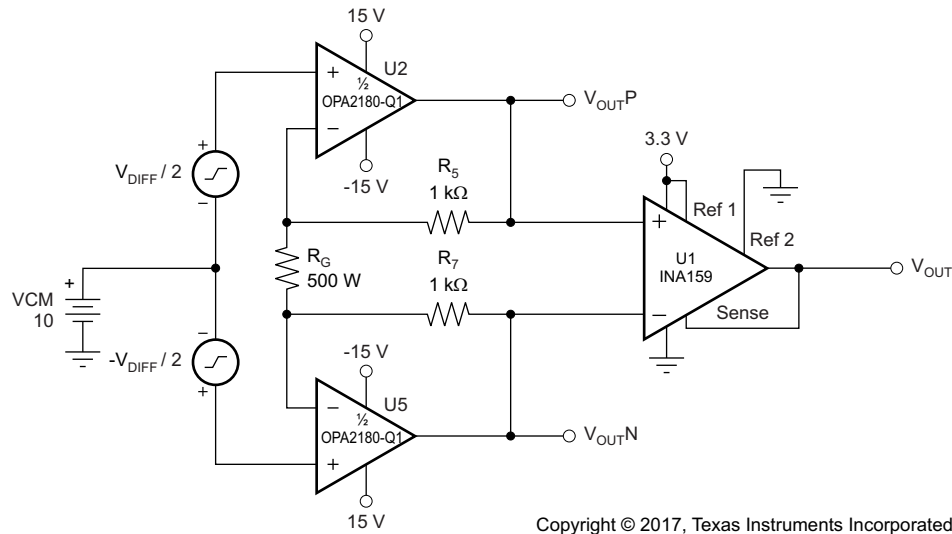
图 32. DC Transfer Characteristic



For step-by-step design procedure, circuit schematics, bill of materials, PCB files, simulation results, and test results, refer to [TI Precision Design T1PD125, Bipolar ±10V Analog Output from a Unipolar Voltage Output DAC](#)

9.2.2 Discrete INA + Attenuation

The OPAx180-Q1 family can be used as a high-voltage, high-impedance front-end for a precision, discrete instrumentation amplifier with attenuation. The INA159 in [Figure 33](#) provides the attenuation that allows this circuit to simply interface with 3.3-V or 5-V analog-to-digital converters (ADCs).

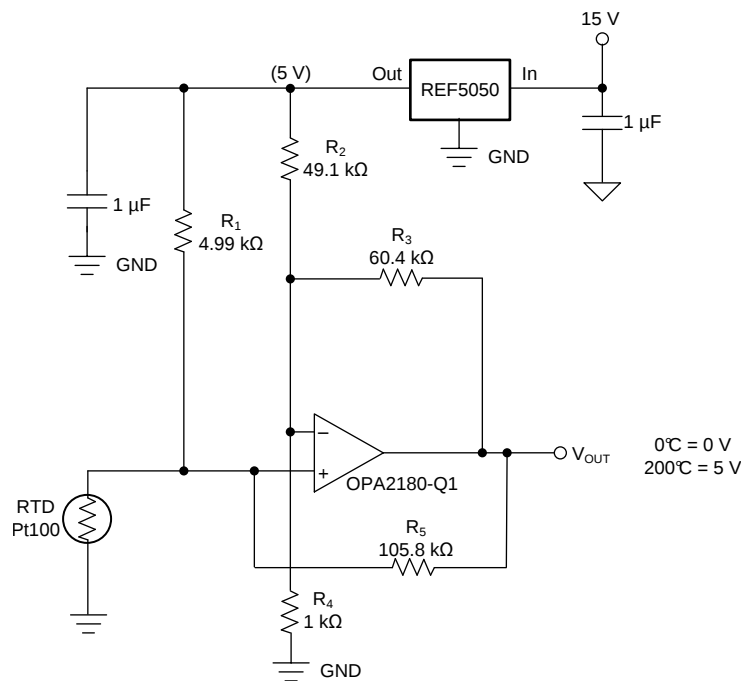


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图 33. Discrete INA + Attenuation for ADC With a 3.3-V Supply

9.2.3 RTD Amplifier

The OPAx180-Q1 is excellent for use in analog linearization of resistance temperature detectors (RTDs). The circuit below ([Figure 34](#)) combines the precision of the OPAx180-Q1 amplifier and the precision reference of the REF5050 to linearize a Pt100 RTD.



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(1) R₅ provides positive-varying excitation to linearize output.

图 34. RTD Amplifier with Linearization

10 Power Supply Recommendations

The OPAx180-Q1 family is specified for operation from 4 V to 36 V (± 2 V to ± 18 V); many specifications apply from -40°C to $+105^{\circ}\text{C}$. Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in [Layout](#)

CAUTION

Supply voltages larger than 40 V can permanently damage the device; see the [Absolute Maximum Ratings](#).

Place 0.1- μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies. For more detailed information on bypass capacitor placement, see [Layout](#).

11 Layout

11.1 Layout Guidelines

For best operational performance of the device, use good printed circuit board (PCB) layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole and op amp itself. Bypass capacitors are used to reduce the coupled noise by providing low-impedance power sources local to the analog circuitry.
 - Connect low-ESR, 0.1- μ F ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are typically devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Take care to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- In order to reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep the input traces separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. As shown in [Figure 35](#), keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.

11.2 Layout Example

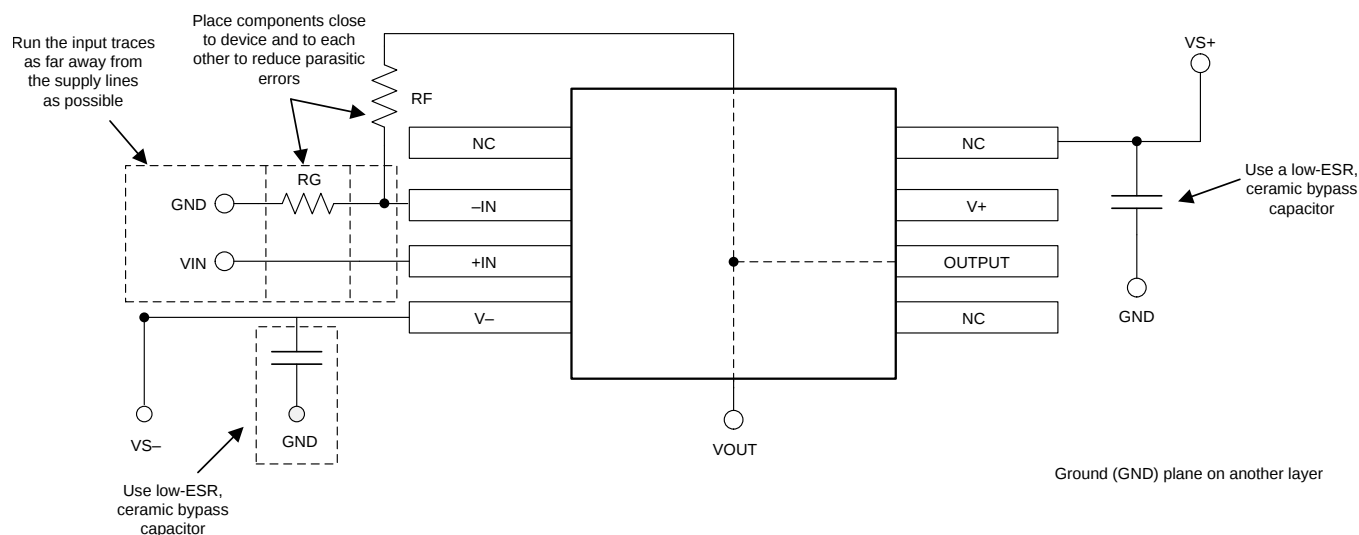


图 35. Operational Amplifier Board Layout for Noninverting Configuration

12 器件和文档支持

12.1 相关链接

表 3 列出了快速访问链接。类别包括技术文档、支持与社区资源、工具和软件，以及申请样片或购买产品的快速链接。

表 3. 相关链接

器件	产品文件夹	立即订购	技术文档	工具与软件	支持和社区
OPA180-Q1	单击此处	单击此处	单击此处	单击此处	单击此处
OPA2180-Q1	单击此处	单击此处	单击此处	单击此处	单击此处

12.2 商标

12.3 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

12.4 术语表

SLYZ022 — *TI* 术语表。

这份术语表列出并解释术语、缩写和定义。

13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此产品说明书的浏览器版本，请查阅左侧的导航栏。

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA180QDGKRQ1	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 105	180	Samples
OPA2180QDGKRQ1	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 105	2180	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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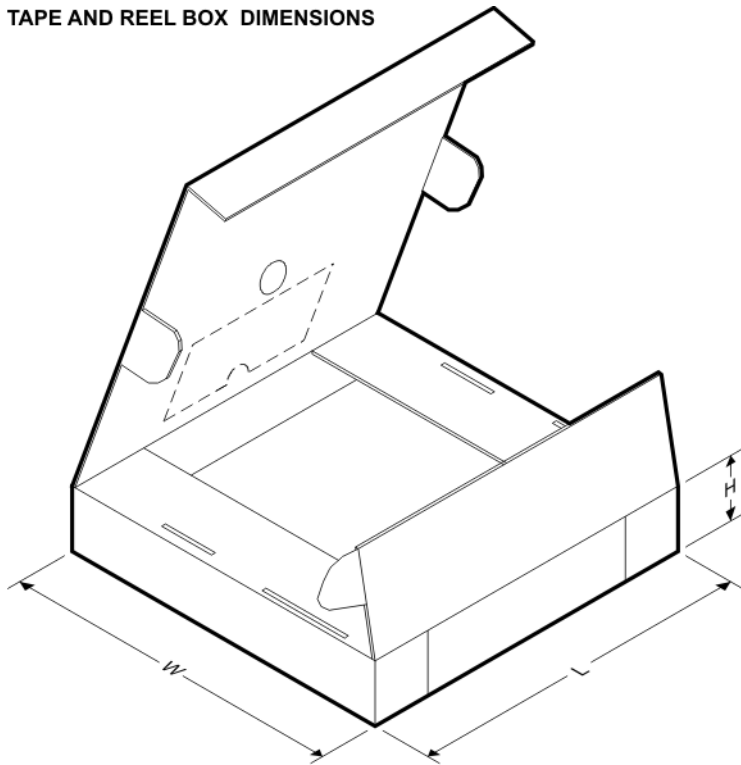
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA180QDGKRQ1	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2180QDGKRQ1	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA180QDGKRQ1	VSSOP	DGK	8	2500	366.0	364.0	50.0
OPA2180QDGKRQ1	VSSOP	DGK	8	2500	366.0	364.0	50.0

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

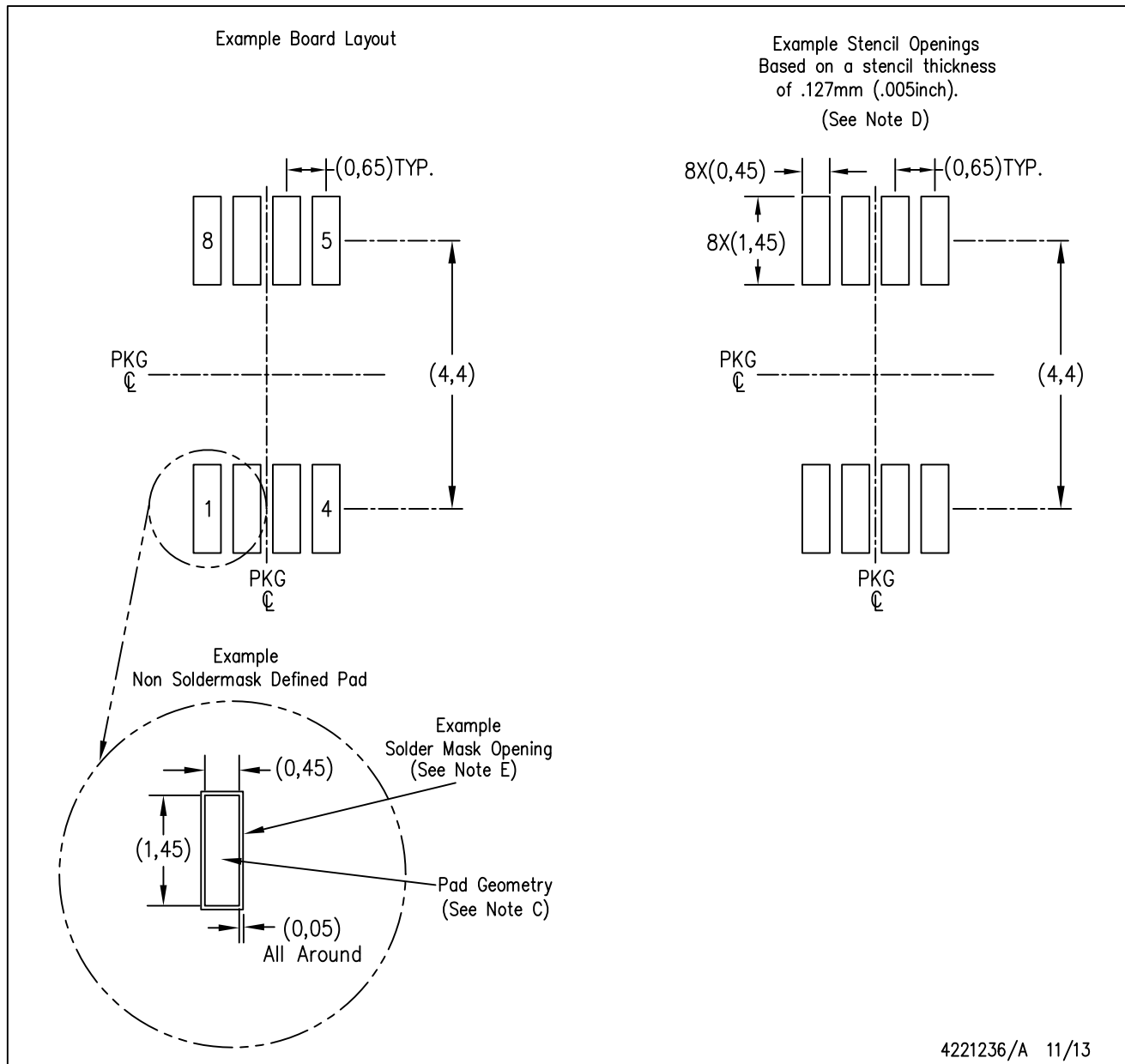


NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.

DGK (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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